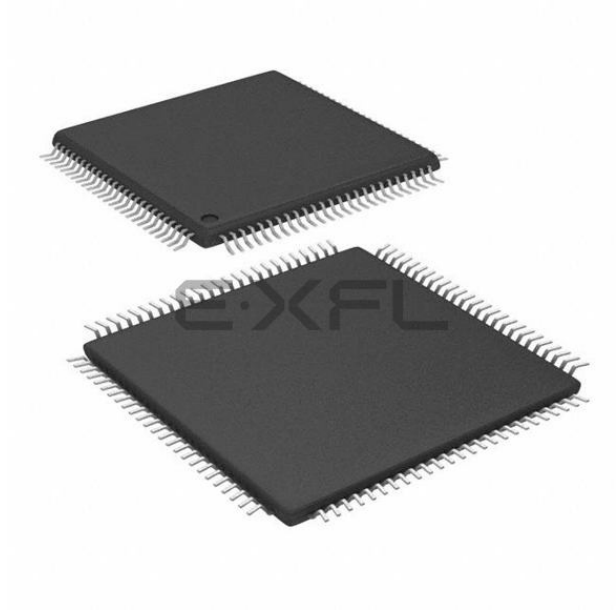
Microchip Technology - PIC32MX450F128LT-V/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	81
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f128lt-v-pt

REGISTER 4-3: BMXDUDBA: DATA RAM USER DATA BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUDBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUDBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDUDBA<15:10>:** DRM User Data Base Address bits

When non-zero, the value selects the relative base address for User mode data space in RAM, the value must be greater than BMXDKPBA.

bit 9-0 **BMXDUDBA<9:0>:** Read-Only bits

Value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 5-4: NVMDATA: FLASH PROGRAM DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMDATA<31:0>:** Flash Programming Data bits

Note: The bits in this register are only reset by a Power-on Reset (POR).

REGISTER 5-5: NVMSRCADDR: SOURCE DATA ADDRESS REGISTER

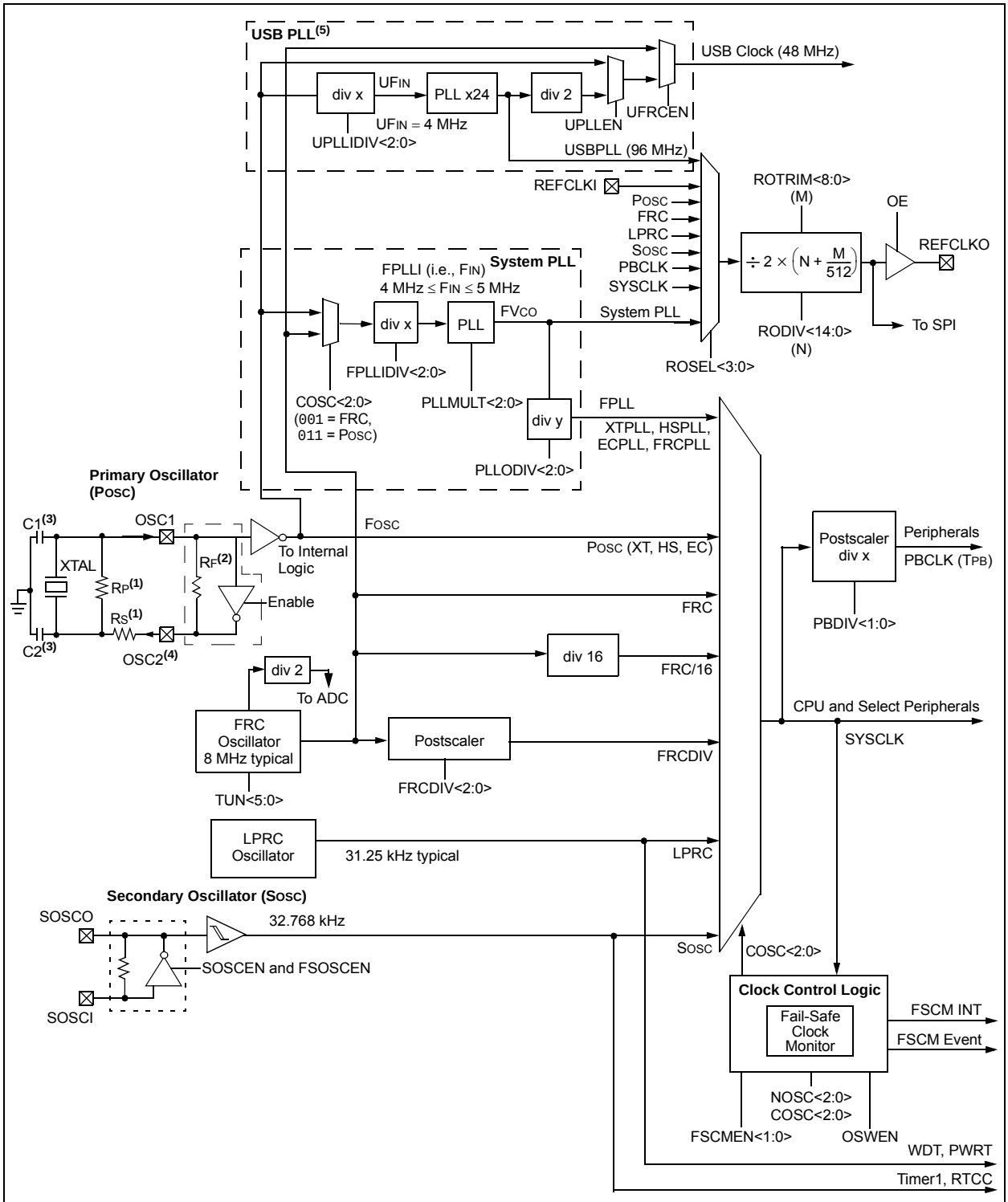
Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMSRCADDR<31:0>:** Source Data Address bits

The system physical address of the data to be programmed into the Flash when the NVMOP<3:0> bits (NVMCON<3:0>) are set to perform row programming.

FIGURE 8-1: PIC32MX330/350/370/430/450/470 FAMILY CLOCK DIAGRAM



Notes:
1. A series resistor, RS, may be required for AT strip cut crystals or eliminate clipping. Alternately, to increase oscillator circuit gain, add a parallel resistor, RP, with a value of 1 MΩ.
2. The internal feedback resistor, RF, is typically in the range of 2 MΩ to 10 MΩ.
3. Refer to **Section 6. "Oscillator Configuration"** (DS60001112) in the "*PIC32 Family Reference Manual*" for help in determining the best oscillator components.
4. PBCLK out is available on the OSC2 pin in certain clock modes.
5. USB PLL is available on PIC32MX4XX devices only.

REGISTER 10-18: DCHxDAT: DMA CHANNEL 'x' PATTERN DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHPDAT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **CHPDAT<7:0>:** Channel Data Register bits

Pattern Terminate mode:
Data to be matched must be stored in this register to allow terminate on match.

All other modes:
Unused.

REGISTER 13-1: T1CON: TYPE A TIMER CONTROL REGISTER (CONTINUED)

bit 2 **TSYNC:** Timer External Clock Input Synchronization Selection bit
When TCS = 1:
1 = External clock input is synchronized
0 = External clock input is not synchronized
When TCS = 0:
This bit is ignored.

bit 1 **TCS:** Timer Clock Source Select bit
1 = External clock from TxCKI pin
0 = Internal peripheral clock

bit 0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

17.1 Control Registers

TABLE 17-1: OUTPUT COMPARE 1 THROUGH OUTPUT COMPARE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxx
		15:0																	xxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxx
		15:0																	xxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxx
		15:0																	xxxx
3220	OC2RS	31:16	OC2RS<31:0>																xxxx
		15:0																	xxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxx
		15:0																	xxxx
3420	OC3RS	31:16	OC3RS<31:0>																xxxx
		15:0																	xxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxx
		15:0																	xxxx
3620	OC4RS	31:16	OC4RS<31:0>																xxxx
		15:0																	xxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxx
		15:0																	xxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 21-2: PMMODE: PARALLEL PORT MODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BUSY	IRQM<1:0>		INCM<1:0>		MODE16	MODE<1:0>	
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	WAITB<1:0>(1)		WAITM<3:0>(1)				WAITE<1:0>(1)	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **BUSY:** Busy bit (Master mode only)
- 1 = Port is busy
- 0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits
- 11 = Reserved, do not use
- 10 = Interrupt generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode) or on a read or write operation when PMA<1:0> =11 (Addressable Slave mode only)
- 01 = Interrupt generated at the end of the read/write cycle
- 00 = No Interrupt generated

bit 12-11 **INCM<1:0>:** Increment Mode bits
- 11 = Slave mode read and write buffers auto-increment (MODE<1:0> = 00 only)
- 10 = Decrement ADDR<15:0> by 1 every read/write cycle(2)
- 01 = Increment ADDR<15:0> by 1 every read/write cycle(2)
- 00 = No increment or decrement of address

bit 10 **MODE16:** 8/16-bit Mode bit
- 1 = 16-bit mode: a read or write to the data register invokes a single 16-bit transfer
- 0 = 8-bit mode: a read or write to the data register invokes a single 8-bit transfer

bit 9-8 **MODE<1:0>:** Parallel Port Mode Select bits
- 11 = Master mode 1 (PMCSx, PMRD/PMWR, PMENB, PMA<x:0>, PMD<7:0> and PMD<8:15>(3))
- 10 = Master mode 2 (PMCSx, PMRD, PMWR, PMA<x:0>, PMD<7:0> and PMD<8:15>(3))
- 01 = Enhanced Slave mode, control signals (PMRD, PMWR, PMCS, PMD<7:0> and PMA<1:0>)
- 00 = Legacy Parallel Slave Port, control signals (PMRD, PMWR, PMCS and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write Strobe Wait States bits(1)
- 11 = Data wait of 4 TPB; multiplexed address phase of 4 TPB
- 10 = Data wait of 3 TPB; multiplexed address phase of 3 TPB
- 01 = Data wait of 2 TPB; multiplexed address phase of 2 TPB
- 00 = Data wait of 1 TPB; multiplexed address phase of 1 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPB cycle for a write operation; WAITB = 1 TPB cycle, WAITE = 0 TPB cycles for a read operation.

2: Address bits, A15 and A14, are not subject to automatic increment/decrement if configured as Chip Select CS2 and CS1.

3: These pins are active when MODE16 = 1 (16-bit mode).

REGISTER 21-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CS2(1)	CS1(3)	ADDR<13:8>					
	ADDR15(2)	ADDR14(4)						
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **CS2:** Chip Select 2 bit(1)
- 1 = Chip Select 2 is active
- 0 = Chip Select 2 is inactive

bit 15 **ADDR<15>:** Destination Address bit 15(2)

bit 14 **CS1:** Chip Select 1 bit(3)
- 1 = Chip Select 1 is active
- 0 = Chip Select 1 is inactive

bit 14 **ADDR<14>:** Destination Address bit 14(4)

bit 13-0 **ADDR<13:0>:** Address bits

Note 1: When the CSF<1:0> bits (PMCON<7:6>) = 10 or 01.
2: When the CSF<1:0> bits (PMCON<7:6>) = 00.
3: When the CSF<1:0> bits (PMCON<7:6>) = 10.
4: When the CSF<1:0> bits (PMCON<7:6>) = 00 or 01.

REGISTER 23-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ 0, this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when ADC is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 24-2: CMSTAT: COMPARATOR STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	—	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	R-0	R-0
	—	—	—	—	—	—	C2OUT	C1OUT

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in IDLE Control bit
- 1 = All Comparator modules are disabled in IDLE mode
- 0 = All Comparator modules continue to operate in the IDLE mode

bit 12-2 **Unimplemented:** Read as '0'

bit 1 **C2OUT:** Comparator Output bit
- 1 = Output of Comparator 2 is a '1'
- 0 = Output of Comparator 2 is a '0'

bit 0 **C1OUT:** Comparator Output bit
- 1 = Output of Comparator 1 is a '1'
- 0 = Output of Comparator 1 is a '0'

TABLE 31-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typ.(2)**	**Max.**	**Units**	**Conditions**	
PIC32MX350F256 Devices Only					
Power-Down Current (IPD) (Note 1)					
DC40k	38	80	µA	-40°C	Base Power-Down Current
DC40l	57	80	µA	+25°C	
DC40n	220	352	µA	+85°C	
DC40m	513	749	µA	+105ºC	
PIC32MX450F256 Devices Only					
Power-Down Current (IPD) (Note 1)					
DC40k	26	42	µA	-40°C	Base Power-Down Current
DC40o	26	42	µA	0°C(5)	
DC40l	26	42	µA	+25°C	
DC40p	250	352	µA	+70°C(5)	
DC40n	250	352	µA	+85°C	
DC40m	513	749	µA	+105ºC	

Note 1: The test conditions for IPD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled
- Voltage regulator is off during Sleep mode (VREGS bit in the RCON register = 0)

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: 120 MHz commercial devices only (0ºC to +70ºC).

FIGURE 31-5: EXTERNAL RESET TIMING CHARACTERISTICS

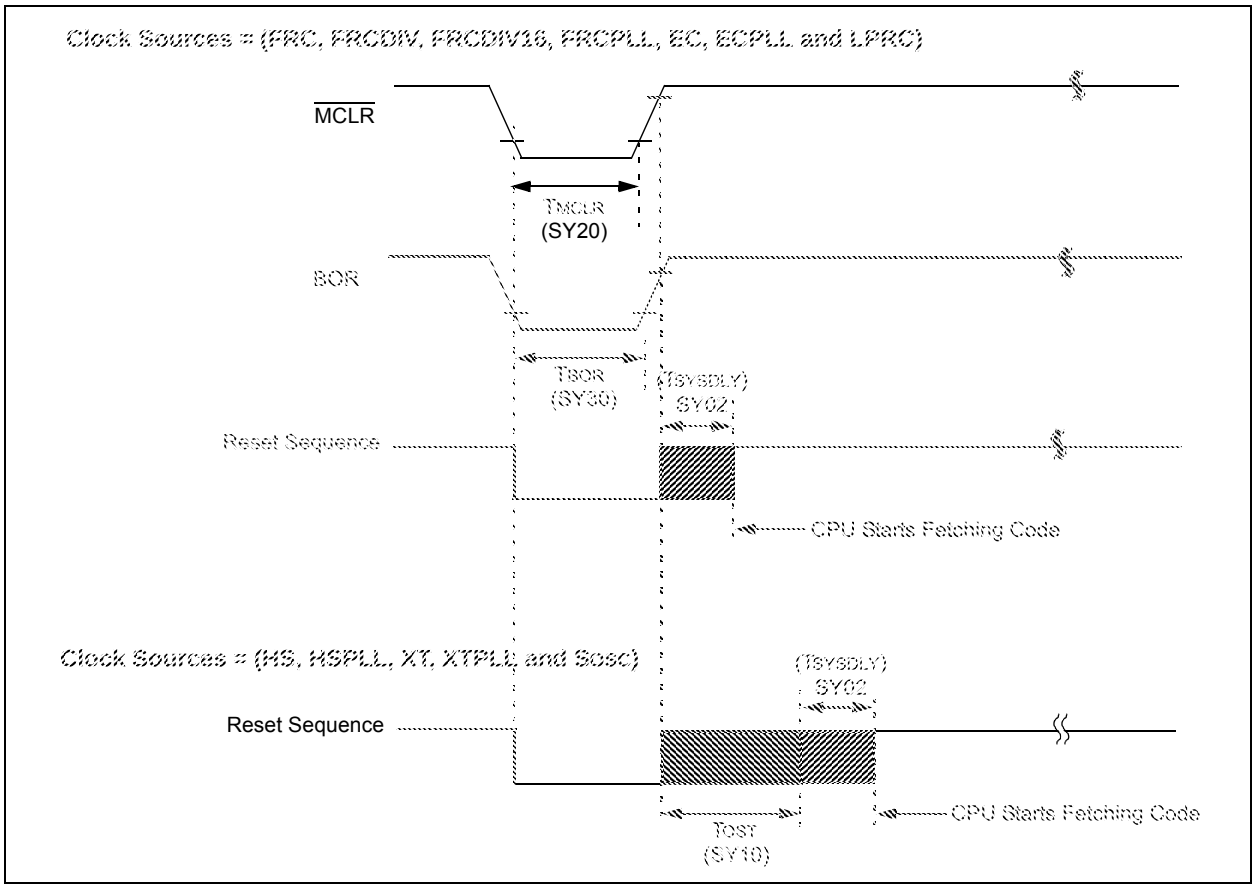


TABLE 31-23: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 μs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

TABLE 31-32: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 4)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	Tsck + 20	—	—	ns	—
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

TABLE 31-37: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period(2)	65	—	—	ns	See Table 31-36
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)(4)	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	2 TAD	—	—	—	—
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger(3)	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)(3)	—	0.5 TAD	—	—	—
AD63	TDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(3)	—	—	2	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

4: Refer to Table 31-36 for detailed conditions.

FIGURE 31-21: PARALLEL MASTER PORT READ TIMING DIAGRAM

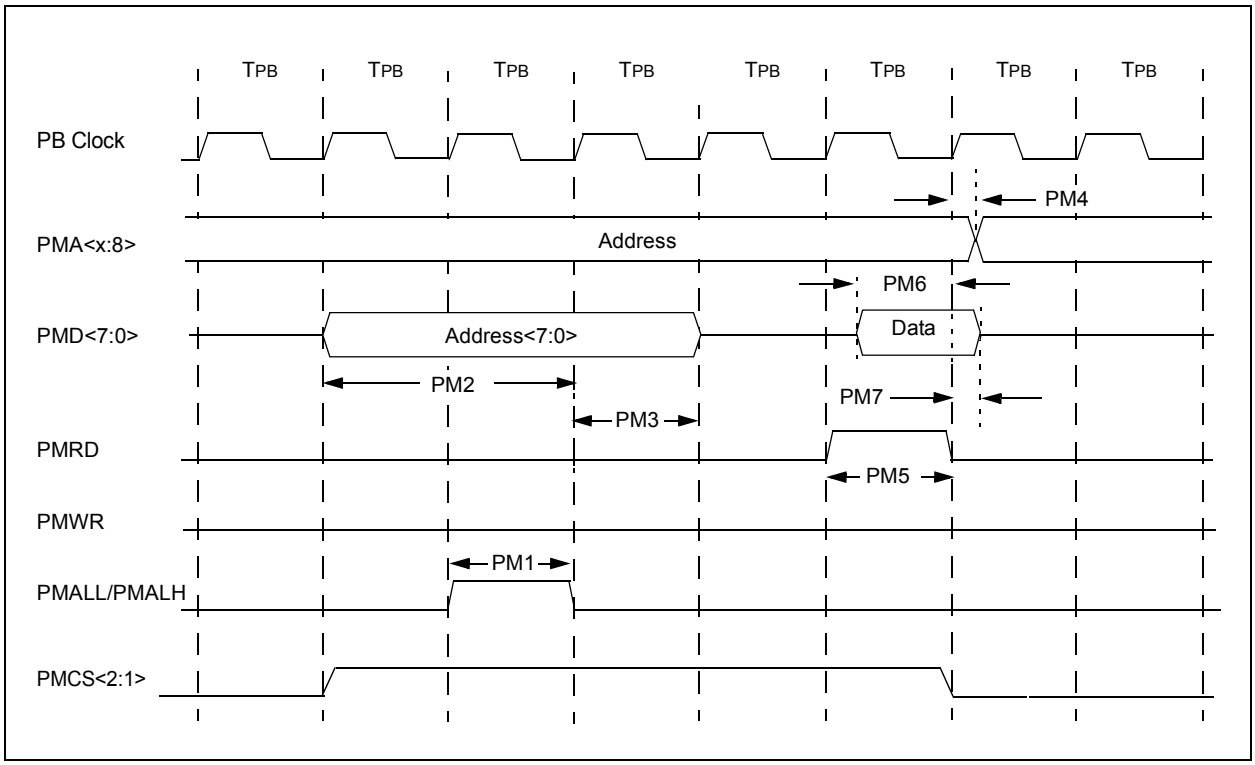


TABLE 31-39: PARALLEL MASTER PORT READ TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PM1	TLAT	PMALL/PMALH Pulse Width	—	1 TPB	—	—	—
PM2	TADSU	Address Out Valid to PMALL/ PMALH Invalid (address setup time)	—	2 TPB	—	—	—
PM3	TADHOLD	PMALL/PMALH Invalid to Address Out Invalid (address hold time)	—	1 TPB	—	—	—
PM4	TAHOLD	PMRD Inactive to Address Out Invalid (address hold time)	5	—	—	ns	—
PM5	TRD	PMRD Pulse Width	—	1 TPB	—	—	—
PM6	TDSU	PMRD or PMENB Active to Data In Valid (data setup time)	15	—	—	ns	—
PM7	TDHOLD	PMRD or PMENB Inactive to Data In Invalid (data hold time)	1 TPB	—	—	—	PMP Clock

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 32-5: TYPICAL IPD CURRENT @ VDD = 3.3V

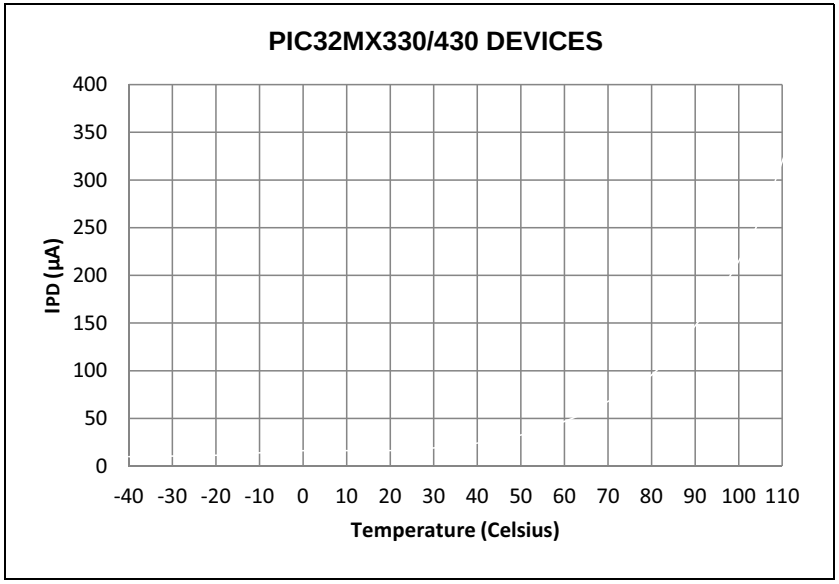


FIGURE 32-6: TYPICAL IPD CURRENT @ VDD = 3.3V

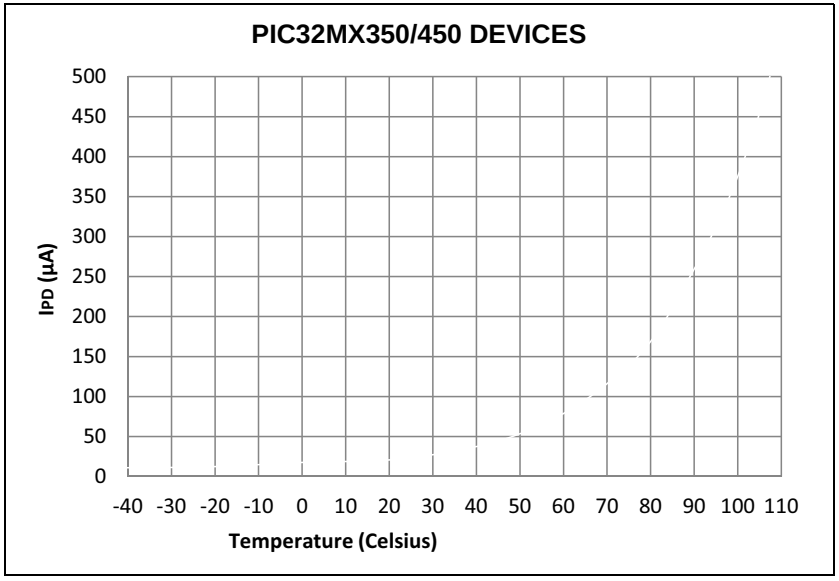


FIGURE 32-7: TYPICAL IPD CURRENT @ VDD = 3.3V

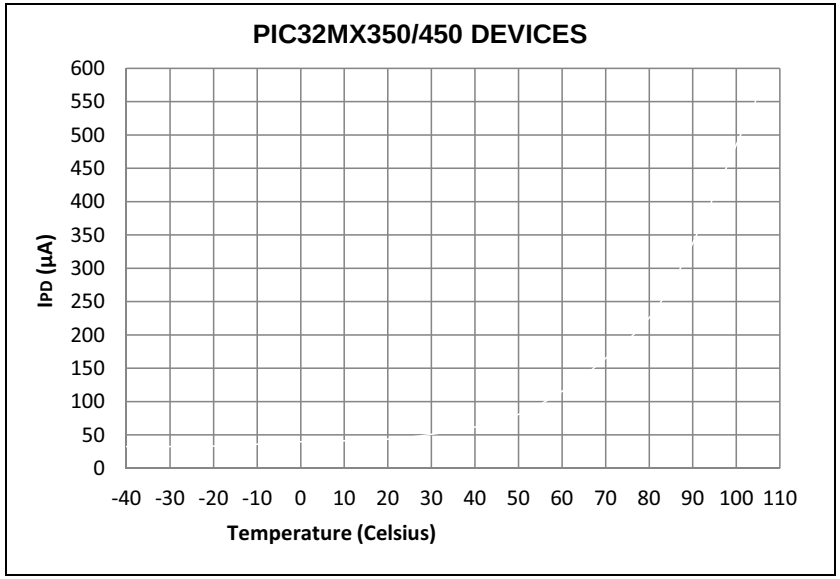
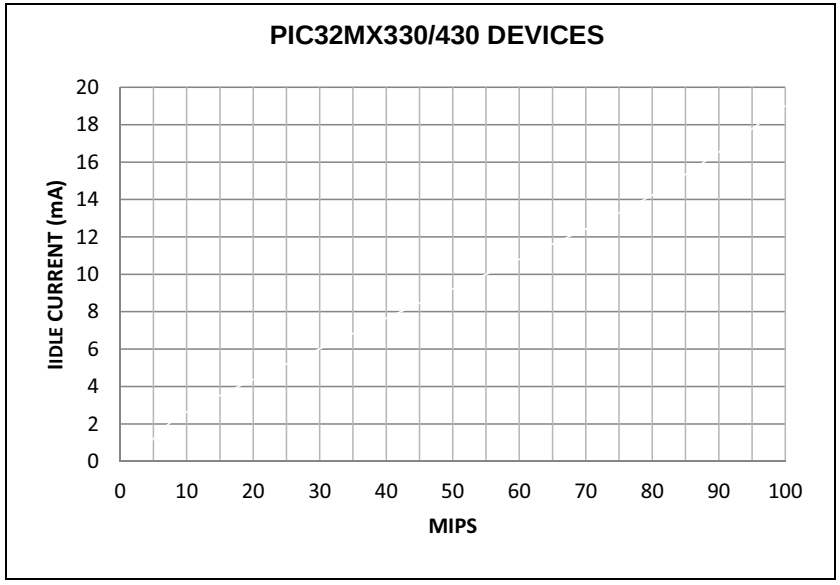


FIGURE 32-8: TYPICAL IIDLE CURRENT @ VDD = 3.3V

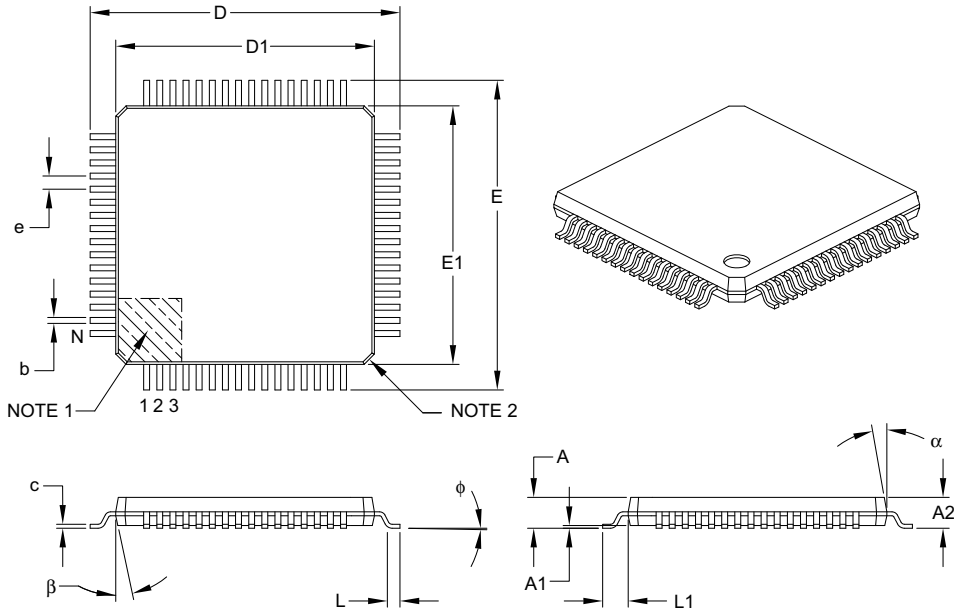


33.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

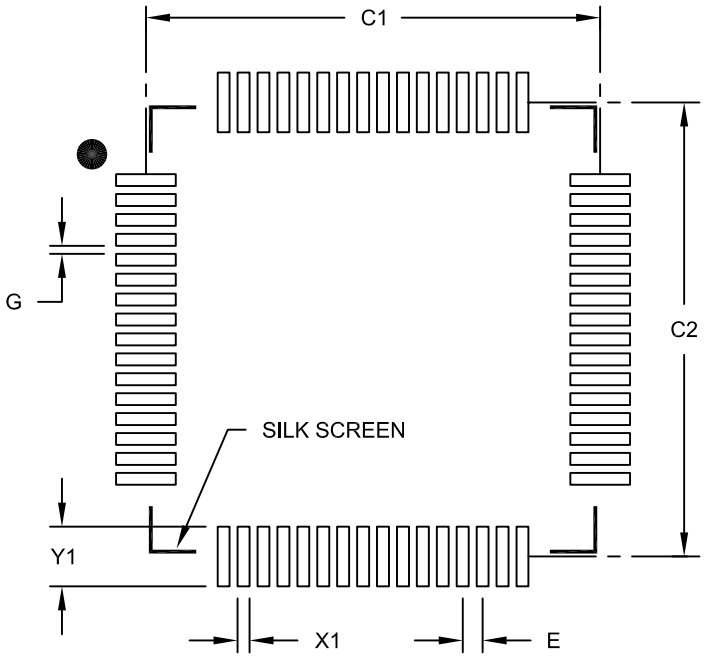
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

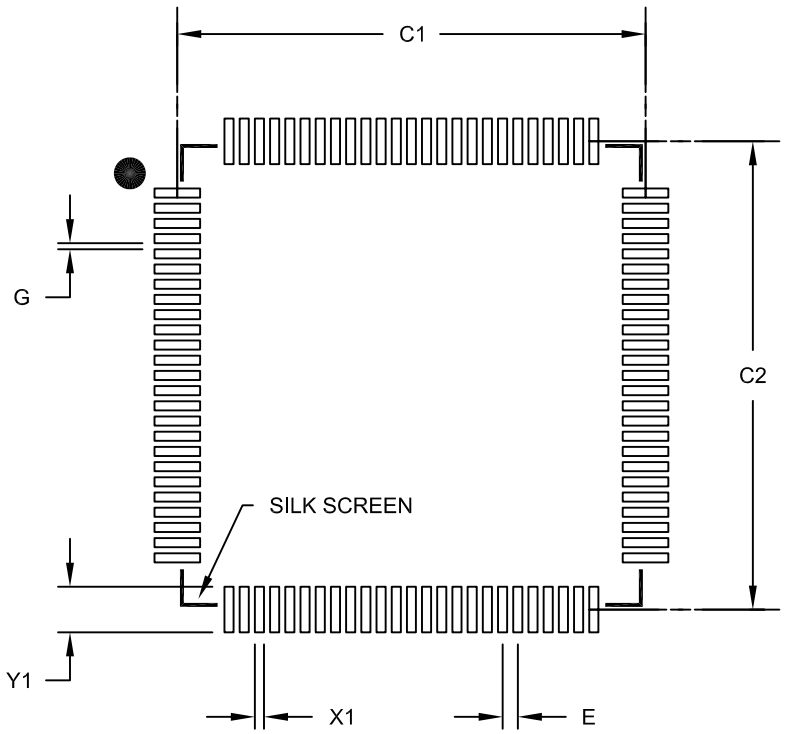
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B